| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|--------------|---|---|---------------------|---------|------------------|
| S27 | 453 | semiconductor and ((capacitor) with ((chip or die or wafer or substrate) near3 level))and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:04 |
| S10 | 334 | semiconductor and ((capacitor) with ((wafer or substrate) near3 level))and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR . | ON | 2005/05/25 18:04 |
| S28 | 329 <u>6</u> | semiconductor and ((capacitor)) and (MIM or MMIC)and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:19 |
| S18 | 62 | semiconductor and ((capacitor)) and ((electrode or plate) with (bump or ball)) and (MIM or MMIC) and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR [*] | ON | 2005/05/25 18:19 |
| S17 | 62 | semiconductor and ((capacitor)) and ((electrode or plate) with (bump or ball)) and (MIM or MMIC)and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:19 |
| S29 | 1384 | semiconductor and ((capacitor)) and ((electrode or plate) with (bump or ball or pad or contact)) and (MIM or MMIC) and @ad<"20031230" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:29 |
| S30 | 1976 | (257/306 or 257/307).ccls. and @ad<"20030730" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:35 |
| S31 | 1166 | (257/310 or 257/311).ccls. and @ad<"20030730" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:36 |
| S32 | 785 | (257/310 or 257/311).ccls. and @ad<"20030730" not S30 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:46 |
| S34 | 671 | (257/758).ccls. and @ad<"20030730" and capacitor | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:48 |
| S33 | 40 | (257/733 or 257/748).ccls. and @ad<"20030730" and capacitor | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:48 |

| S26 | 8 | (("6184567") or ("6881996") or ("6784478") or ("20050063135")). PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/05/25 18:53 |
|-----|------|---|---|----|-----|------------------|
| S35 | 5 | (on-chip adj capacitor) and Leung. inv. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/25 18:54 |
| S36 | 1871 | ((257/532) or (257/535)).CCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/05/26 15:54 |
| S37 | 1724 | (257/532 or 257/535).ccls. and @ad<"20030730" | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2005/05/26 15:55 |